ARIZONA MICROTEK, INC.

AZ10ELT20
AZ100ELT20

CMOS/TTL to Differential PECL Translator

FEATURES

- 0.5ns Typical Propagation Delay
- Differential PECL Outputs
- Flow Through Pinouts
- Operating Range of +3.0V to +5.5V
- Direct Replacement for ON Semi MC100ELT20 & Micrel SY89329V
- Available in 2x2 and 3x3 mm MLP Packages

PACKAGE AVAILABILITY

PACKAGE	PART NUMBER	MARKING	NOTES
MLP 8 (2x2x0.75)	AZ100ELT20N	T0 <Date Code>	1,2
MLP 8 (2x2x0.75) RoHS Compliant / Lead (Pb) Free	AZ100ELT20N+	T0+ <Date Code>	1,2
MLP 16 (3x3)	AZ10/100ELT20L	AZM T20 <Date Code>	1,2
MLP 16 (3x3) Lead-Free	AZ10/100ELT20L+	AZM+ T20 <Date Code>	1,2
SOIC 8	AZ10ELT20D	AZM10 ELT20	1,2,3
SOIC 8	AZ100ELT20D	AZM100 ELT20	1,2,3
TSSOP 8	AZ100ELT20T	AZH LT20	1,2,3
TSSOP 8 RoHS Compliant / Lead (Pb) Free	AZ100ELT20T+	AZH+ LT20	1,2,3
DIE	AZ10/100ELT20XP	N/A	4

1 Add R1 at end of part number for 7 inch (1K parts), R2 for 13 inch (2.5K parts) Tape & Reel.
2 Date code format: "Y" or "YY" for year followed by "WW" for week.
3 Date code "YWW" or "YYWW" on underside of part.
4 Waffle Pack.

DESCRIPTION

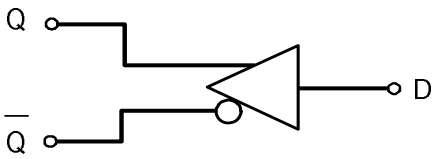
The AZ10/100ELT20 is a CMOS/TTL to differential PECL translator. It operates with a single power supply of +3.0 to +5.5 volts, making it ideal for both LVCMOS/LVTTL and CMOS/TTL applications. The extremely small MLP 8 2x2 mm package makes it ideal for those applications where space, performance and low power are at a premium.

When the D input is left floating, the Q output is forced HIGH, and the $\overline{Q}$ output is forced LOW.

The ELT20 is available in both PECL standards: the AZ10ELT20 is compatible with PECL 10K logic levels while the AZ100ELT20 is compatible with PECL 100K logic levels.

NOTE: Specifications in the PECL tables are valid when thermal equilibrium is established.

BLOCK DIAGRAM



1630 S. STAPLEY DR., SUITE 125 • MESA, ARIZONA 85204 • USA • (480) 962-5881 • FAX (480) 890-2541
www.azmicrotek.com

Absolute Maximum Ratings are those values beyond which device life may be impaired.

Symbol	Characteristic		Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		0 to +8.0	V
V_{IN}	Input Voltage		0 to +6.0	V
I_{OUT}	Current Applied to Output in Low Output State	— Continuous — Surge	50 100	mA
T_A	Operating Temperature Range (In Free-Air)		-40 to +85	°C
T_{STG}	Storage Temperature Range		-65 to +150	°C

TTL/CMOS INPUT DC CHARACTERISTICS (GND = 0.0V, V_{CC} = +3.0V to +5.5V)

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
I_{IH}	Input HIGH Current			15	µA	V_{IN} = 2.7V
I_{IHH}	Input HIGH Current			20	µA	V_{IN} = V_{CC}
I_{IL}	Input LOW Current			-0.1	mA	V_{IN} = 0.5V
V_{IK}	Input Clamp Diode Voltage			-1.2	V	I_{IN} = -18mA
V_{IH}	Input HIGH Voltage	2.0			V	
V_{IL}	Input LOW Voltage			0.8	V	

10K LVPECL DC Characteristics (GND = 0.0V, V_{CC} = +3.3V)

Symbol	Characteristic	-40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage[1,2]	2220		2410	2280		2460	2320		2490	2390		2580	mV
V_{OL}	Output LOW Voltage[1,2]	1350		1650	1350		1670	1350		1670	1350		1705	mV
I_{CC}	Power Supply Current[3]			16			16			16			16	mA

1. Output parameters vary 1:1 with V_{CC}.
2. Each output is terminated through a 50Ω resistor to V_{CC} – 2V.
3. I_{CC} measurements must be done with outputs open.

10K PECL DC Characteristics (GND = 0.0V, V_{CC} = +5.0V)

Symbol	Characteristic	-40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage[1,2]	3920		4110	3980		4160	4020		4190	4090		4280	mV
V_{OL}	Output LOW Voltage[1,2]	3050		3350	3050		3370	3050		3370	3050		3405	mV
I_{CC}	Power Supply Current[3]			16			16			16			16	mA

1. Output parameters vary 1:1 with V_{CC}.
2. Each output is terminated through a 50Ω resistor to V_{CC} – 2V.
3. I_{CC} measurements must be done with outputs open.

100K LVPECL DC Characteristics (GND = 0.0V, V_{CC} = +3.3V)

Symbol	Characteristic	-40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage[1,2]	2220		2420	2275		2420	2275		2420	2275		2420	mV
V_{OL}	Output LOW Voltage[1,2]	1400		1750	1400		1680	1400		1680	1400		1680	mV
I_{CC}	Power Supply Current[3]			16			16			16			16	mA

1. Output parameters vary 1:1 with V_{CC}.
2. Each output is terminated through a 50Ω resistor to V_{CC} – 2V.
3. I_{CC} measurements must be done with outputs open.

100K PECL DC Characteristics (GND = 0.0V, V_{CC} = +5.0V)

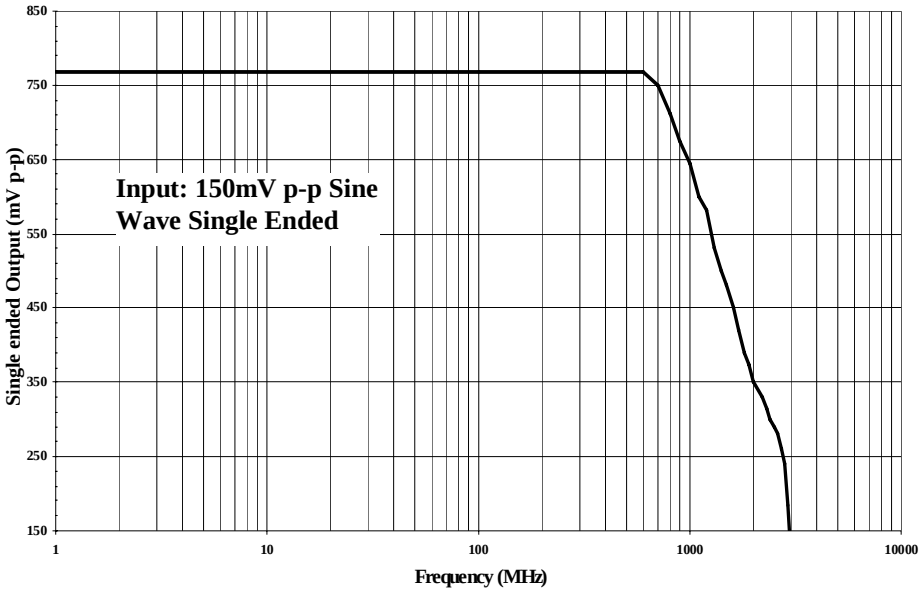
Symbol	Characteristic	-40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage[1,2]	3920		4120	3975		4120	3975		4120	3975		4120	mV
V_{OL}	Output LOW Voltage[1,2]	3100		3450	3100		3380	3100		3380	3100		3380	mV
I_{CC}	Power Supply Current[3]			16			16			16			16	mA

1. Output parameters vary 1:1 with V_{CC}.
2. Each output is terminated through a 50Ω resistor to V_{CC} – 2V.
3. I_{CC} measurements must be done with outputs open.

AC CHARACTERISTICS (GND = 0.0V, V_{CC} = +3.0V to +5.5V)

Symbol	Characteristic	-40°C		0°C		25°C			85°C		Unit	Condition
		Min	Max	Min	Max	Min	Typ	Max	Min	Max		
t_{PLH}/t_{PHL}	Propagation Delay[1]	100	600	100	600	100		600	100	600	ps	
t_r/t_f	Output Rise/Fall Time	200	500	200	500	200		500	200	500	ps	20-80%
f_{MAX}	Maximum Frequency[2]	800		800		800			800		MHz	

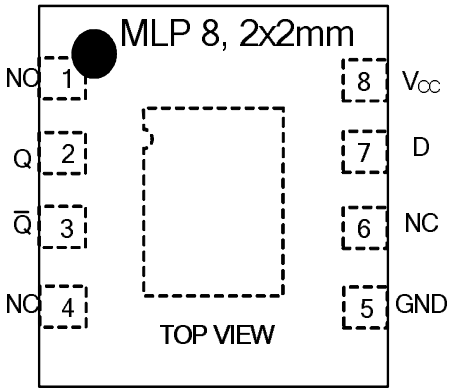
1. Propagation delay is measured from +1.5V on the input to 50% of the PECL output swing. Input rise/fall times are < 1ns/V.
2. Output at –3 dB.



Large Signal Bandwidth

PIN DESCRIPTION

PIN	FUNCTION
Q, $\overline{Q}$	Differential PECL Outputs
D	TTL/CMOS Input
GND	Ground
V_{CC}	Positive Supply
NC	No Connect, Leave Open Except as Noted
10K	10K/100K Mode Select

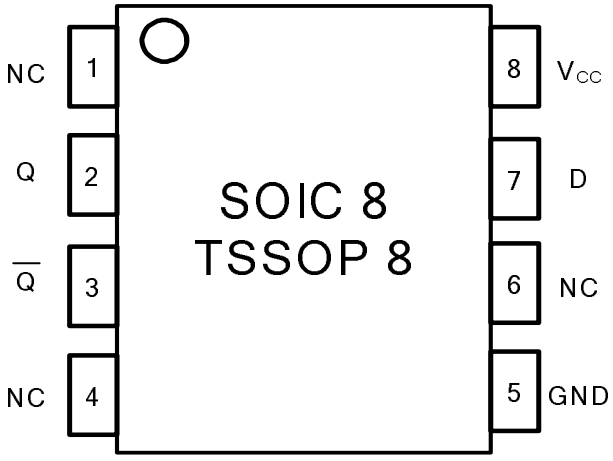


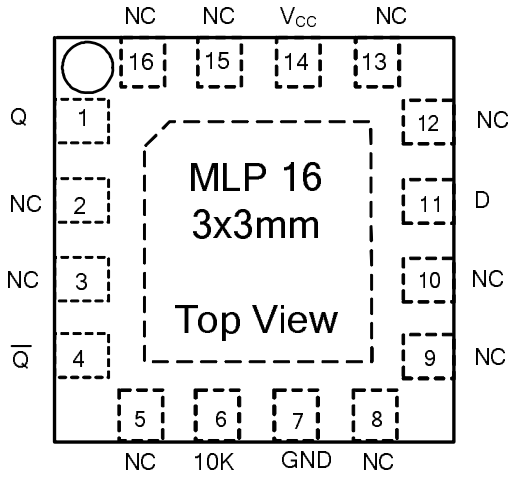
MLP 16 Package and DIE: 10K/100K Selection

Connect pin/pad 10K to GND to select 10K operation. Float (NC) pin/pad 10K to select 100K operation. GND connection must be less than 1Ω.

Pin 8 of the MLP 16 package may be connected to pin 7 (GND) with no effect on the circuit.

Leave Center Botom Pad open or connect to GND.

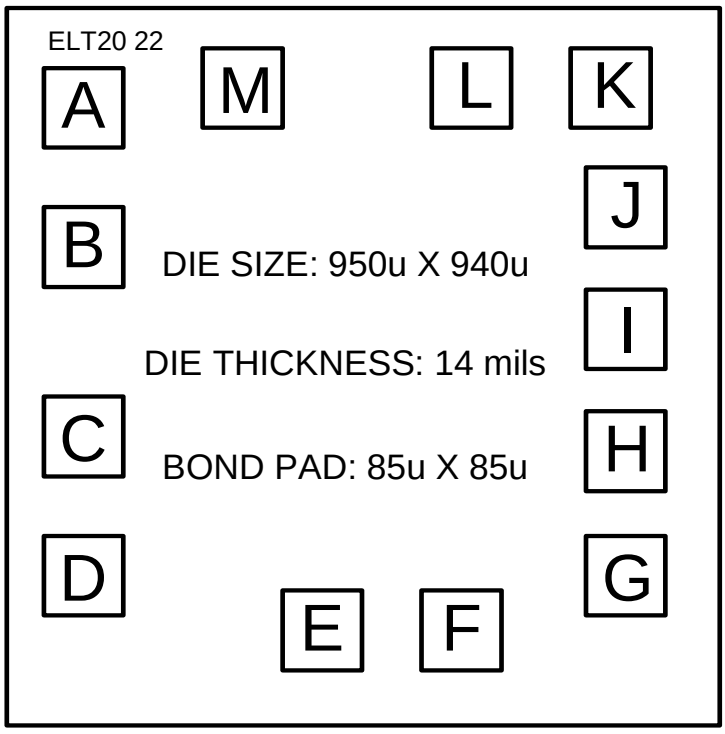




Leave Center Bottom Pad open or connect to GND.

DIE PAD COORDINATES

AZ10/100ELT20 DIE:



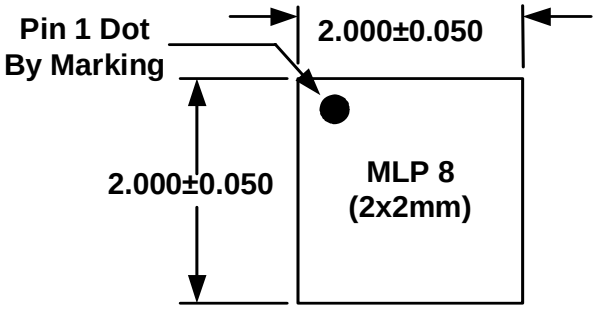
Note: Other die thicknesses available. Contact factory for further information.
The die backside may be left open or connected to GND.

PAD CENTER COORDINATES

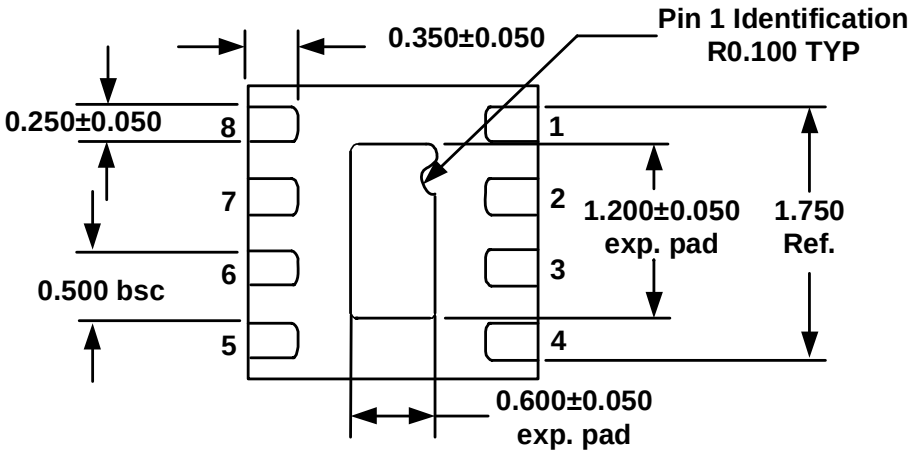
NAME	PAD DESIGNATION	X(Microns)	Y(Microns)
A	NC	-342.5	312.5
B	NC	-342.5	144.5
C	D	-342.5	-87.0
D	NC	-342.5	-255.0
E	V_{CC}	-33.5	-312.5
F	V_{CC}	126.5	-312.5
G	Q	312.5	-248.5
H	$\bar{Q}$	312.5	-98.5
I	NC	312.5	51.5
J	NC	312.5	201.5
K	NC	302.5	342.5
L	10K	142.5	342.5
M	GND	-140.5	342.5

NC = No connect, leave open.

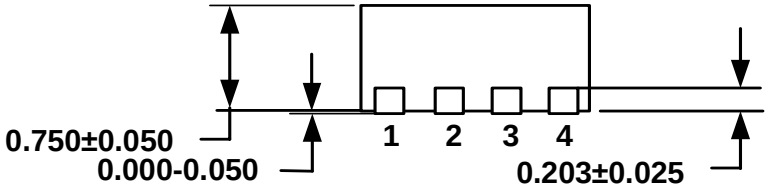
PACKAGE DIAGRAM
MLP 8 2x2mm



TOP VIEW



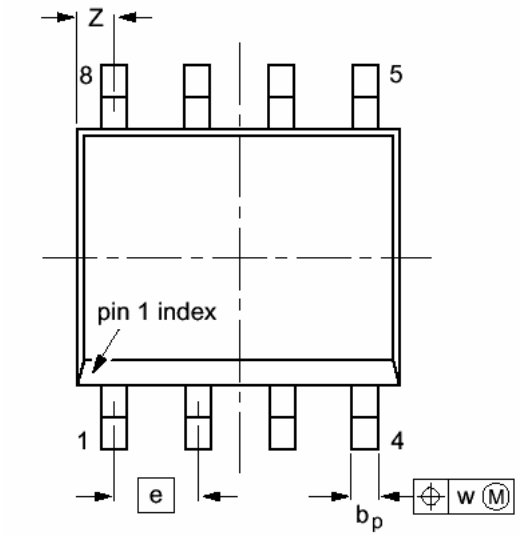
BOTTOM VIEW

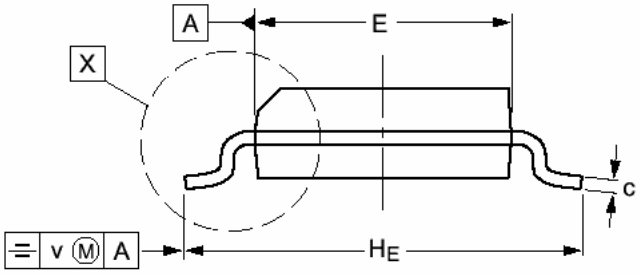


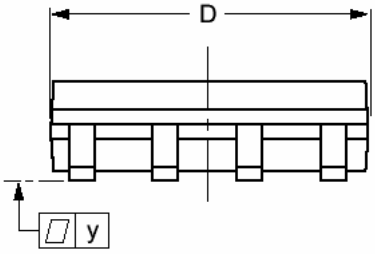
SIDE VIEW

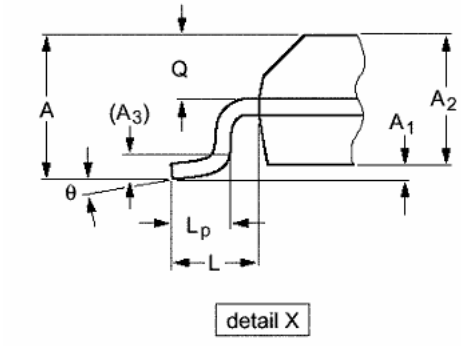
Note: All dimensions are in mm

PACKAGE DIAGRAM
SOIC 8





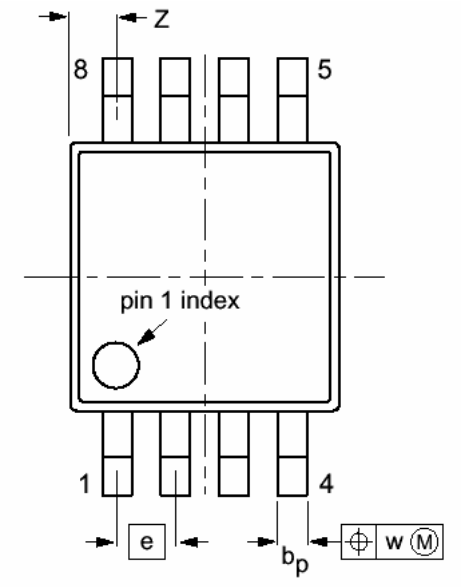


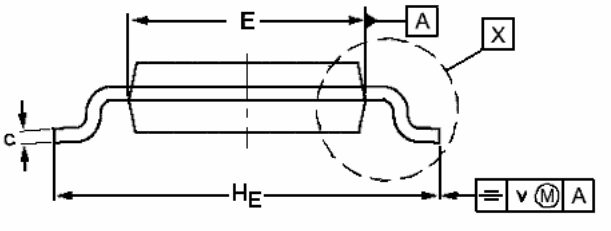


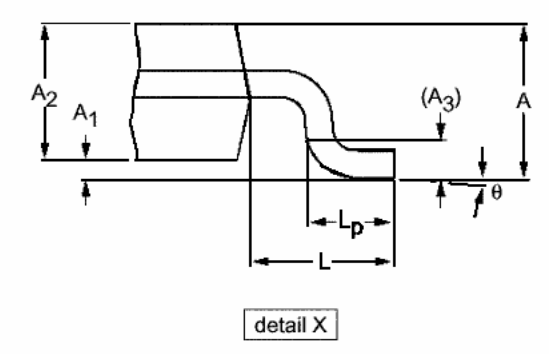
NOTES:
1. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
2. MAXIMUM MOLD PROTRUSION FOR D IS 0.15mm.
3. MAXIMUM MOLD PROTRUSION FOR E IS 0.25mm.

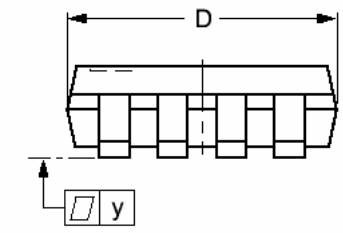
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	.053	0.069
A_1	0.10	0.25	0.004	0.010
A_2	1.28	1.57	0.050	0.062
A_3	0.25		0.01	
b_p	0.36	0.49	0.014	0.019
c	0.19	0.25	0.0075	0.0100
D	4.80	5.00	0.19	0.20
E	3.80	4.00	0.15	0.16
e	1.27		0.050	
H_E	5.80	6.20	0.228	0.244
L	1.05		0.041	
L_p	0.40	1.27	0.016	0.050
Q	0.60	0.70	0.024	0.028
v	0.25		0.01	
w	0.25		0.01	
y	0.10		0.004	
Z	0.30	0.70	0.012	0.028
θ	0^O	8^O	0^O	8^O

PACKAGE DIAGRAM
TSSOP 8





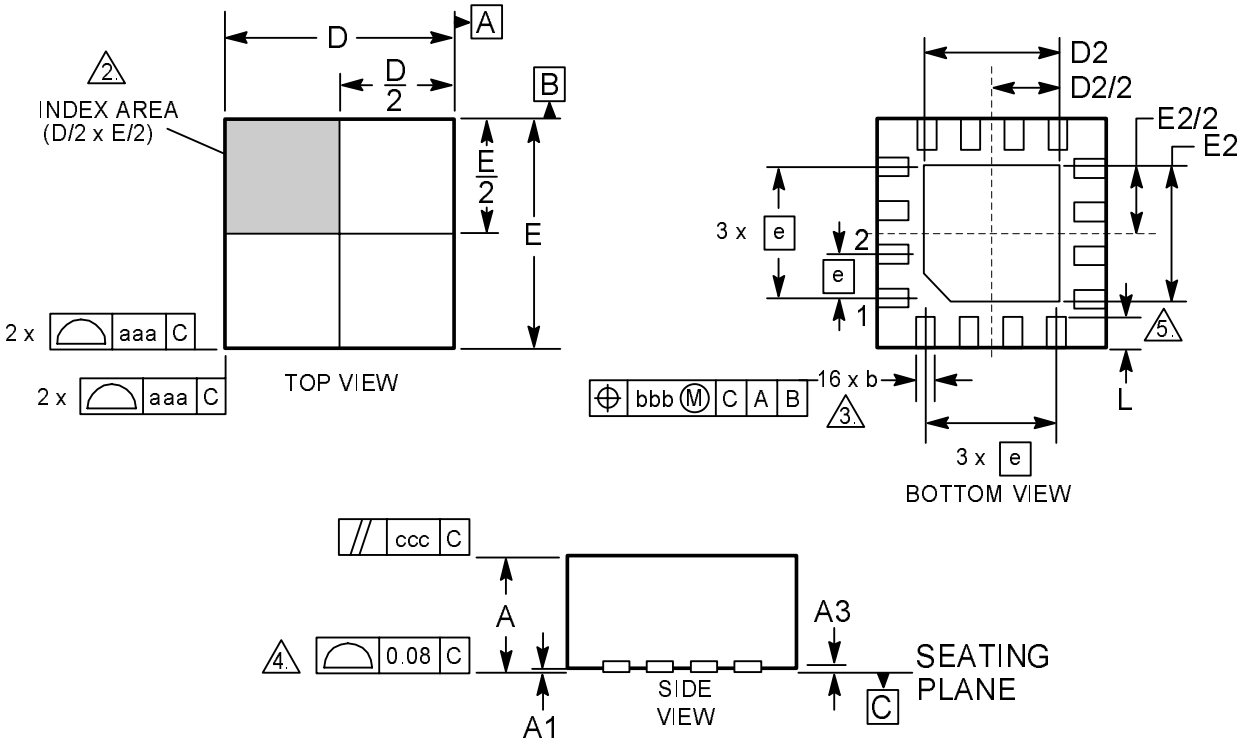




DIM	MILLIMETERS	
	MIN	MAX
A		1.10
A_1	0.05	0.15
A_2	0.75	0.95
A_3	0.25	
b_p	0.22	0.40
c	0.13	0.23
D	2.90	3.10
E	2.90	3.10
e	0.65	
H_E	4.75	5.05
L	0.95	
L_p	0.40	0.70
v	0.10	
w	0.08	
y	0.10	
Z	0.38	0.64
θ	0^O	6^O

NOTES:
1. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
2. MAXIMUM MOLD PROTRUSION FOR D IS 0.15mm.
3. MAXIMUM MOLD PROTRUSION FOR E IS 0.25mm.

PACKAGE DIAGRAM
MLP 16 3x3mm



NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME T14-1994.
2. THE TERMINAL #1 AND PAD NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012.
3. DIMENSION b APPLIES TO METALLIZED PAD AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM PAD TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
5. INSIDE CORNERS OF METALLIZED PAD MAY BE SQUARE OR ROUNDED

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	0.80	1.00
A1	0.00	0.05
A3	0.25 REF	
b	0.18	0.30
D	2.90	3.10
D2	0.25	1.95
E	2.90	3.10
E2	0.25	1.95
e	0.50 BSC	
L	0.30	0.50
aaa	0.25	
bbb	0.10	
ccc	0.10	

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